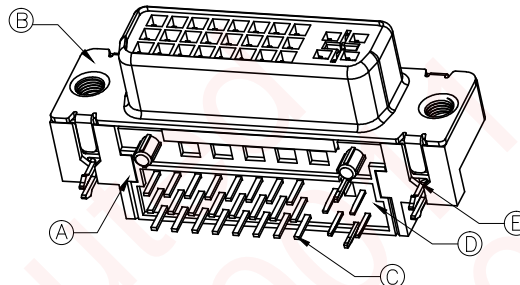
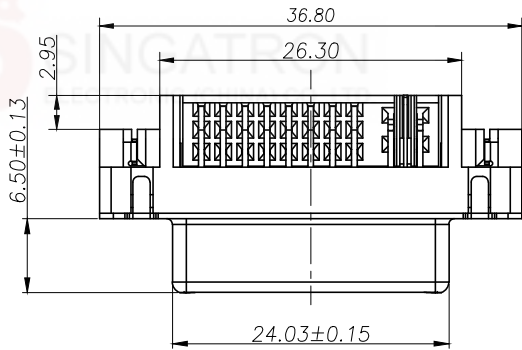
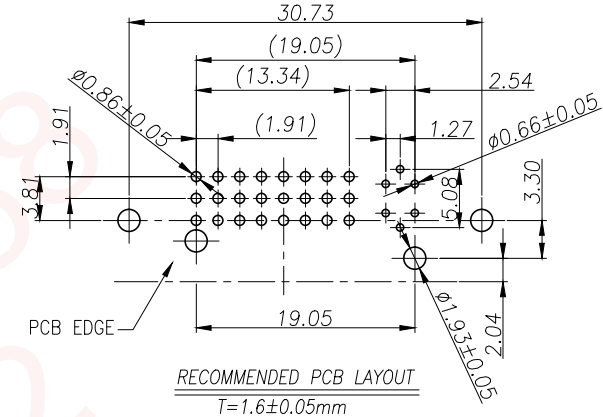
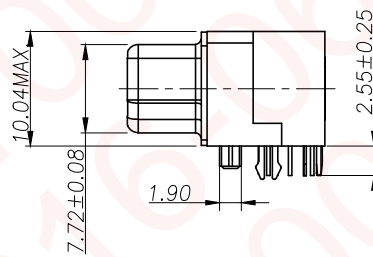
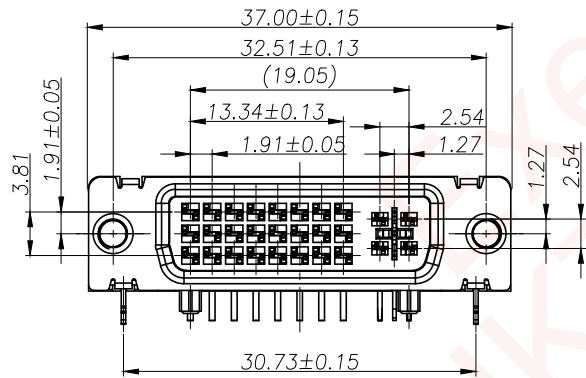


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO:S160408-10A	jttlucky	2016.06.23

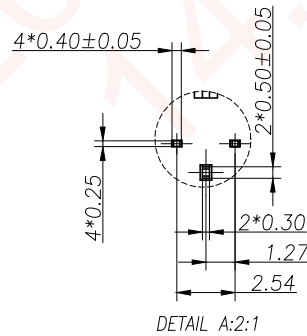
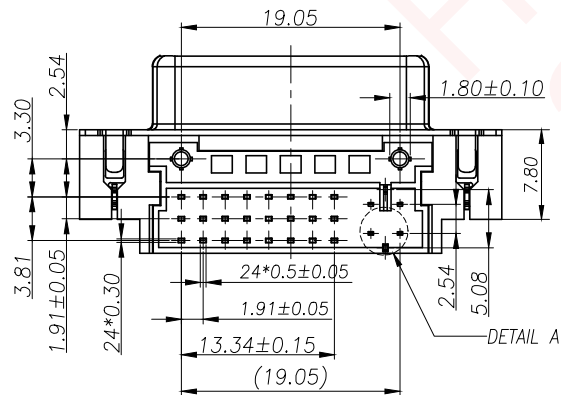


3D VIEW

NOTE:
 1.MATERIAL:
 INSULATOR:HIGH TEMPERATURE+30%GLASS FIRBE UL94V-0
 TERMINAL: COPPER ALLOY
 TERMINAL PLATING:SELECTIVE GOLG PLATING ONAREA.
 TIN 100U"MIN.ON SOLDER TAIL.
 SEHLL:SPCC-SD NICKEL PLATING.
 GROUNDING CLIP:BRASS TIN PALTING.
 NUT: COPPER ALLOY. NICKEL PLATING.
 2.ELECTRICAL:
 INSULATOR RESISTANCE:1000MEG OHMS MIN.
 DIELECTRIC WITHSTANDING VOLTAGE:500V AC RMS.
 VOLTAGE TATING:40V AC RMS.CONTINUOUS MAX.
 CURRENT RATING:1.5A MIN. 3.0A MAX.
 CONTACT RESISTANCE:30 MILLIOHMS MAX.
 3.ENVIRONMENTAL
 TEMPERATURE RANGE:-20°C TO +85°C.



RECOMMENDED PCB LAYOUT
 T=1.6±0.05mm



E	BoardLock	2	Alloy	NICKEL and NIN MIN 60u"MIN
D	COVER	1	HIGH TEMPERATURE	WHITE
C	TERMINAL	29	COPPER ALLOY T=0.30	G/F Au ON MATING AREA, 100u"MIN IN PLATED ON SOLDERING 50u"NICKEL UNDER PLATING OVERALL
B	SHELL	1	SPCC T=0.50	NICKEL 60u"MIN
A	HOUSING	1	HIGH TEMPERATURE	WHITE
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
UNLESS OTHERWISE SPECIFIED TOLERANCES		Singatron Enterprise Co., Ltd. 信音企業股份有限公司		
DECIMALS:		TITLE		
X	:±0.5	DVI 单层24+5		
X.X	:±0.3	DWN	jttlucky	PART NO. 2DS3Y48-029112H
X.XX	:±0.2	CHKD	james	SCALE 4:1 UNIT: mm
		APVD	boye	SIZE: A3 SHEET:1 OF 1 REV: A
CUSTOMER COPY				